

PRODUCT/PROCESS CHANGE NOTIFICATION

PCN MPA/06/2113 Notification Date 10/30/2006

New Molding compound for TO-220 (Samsung Cheil SI7200DXC)

MPA - MPA

Table 1. Change Identification

Product Identification (Product Family/Commercial Product)	See attached list
Type of change	Package assembly material change
Reason for change	to have an alternative source
Description of the change	MPA Group is ready to announce in addition to the resin currently used, a new molding compound which will be used in internal Plant Casablanca and Shenzhen. The new molding compound (Samsung Cheil SI7200DXC) will be used in TO-220 assembly process and it will impact in Power Mosfet, Power Bipolar and Voltage Regulators devices produced in that package. ST ensures the traceability of new resin at lot level. No change in processes or performance, while in the meantime we will improve quality and service.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Traceability is ensured at lot level
Manufacturing Location(s)	1]St Ain Sebaa - Morocco 2]St Shenzhen -China

Table 2. Change Implementation Schedule

Forecasted implementation date for change	20-Jan-2007
Forecasted availability date of samples for customer	10-Oct-2006
Forecasted date for STMicroelectronics change Qualification Plan results availability	10-Oct-2006
Estimated date of changed product first shipment	20-Jan-2007

47/.

Table 3. Change Responsibility

	Name	Signature	Date
Division Product Manager	Porto/Pesce/Wilson		Oct.24 ,06
Division Q.A. Manager	Falcone/Vitali		Oct.24 ,06
Division Marketing Manager	Carlo Marino		Oct.24 ,06

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Customer Part numbers list	
Qualification Plan results	

Customer Acknowledgement of Receipt	PCN MPA/06/2113
Please sign and return to STMicroelectronics	Sales Office Notification Date 10/30/2006
□ Qualification Plan Denied	Name:
□ Qualification Plan Approved	Title:
	Company:
□ Change Denied	Date:
□ Change Approved	Signature:
Remark	

47/.



Date:	May '06
No	01a/06

RELIABILITY EVALUATION ON

TO-220 made with

Samsung Cheil SI7200DXC Mold Compound

ISSUED BY	RELIABILITY DEPARTMENT	Page 1 of 21
-----------	---------------------------	--------------



Date:	May '06
No	01a/06

Table of Contents

1.	Introduction	pg.	3
2.	Test vehicles	pg.	4
3.	Failure Criteria	pg.	5
4.	Evaluation plan and results	pg.	6
5.	Appendixes		
	- Technological Characteristics	pg.	13
	- Reliability Test Description	pg.	19

ISSUED BY	RELIABILITY DEPARTMENT	Page 2 of 21
-----------	---------------------------	--------------



Date:	May '06
No	01a/06

Introduction

This report is aimed to qualify the package TO-220 made in ST Shenzhen and Casablanca Plants with Samsung Cheil SI7200DXC Mold Compound.

The Qualification Reliability test trials have been performed in ST Catania Site.

The evaluation results met ST products qualification targets, therefore the TO-220 Package version with the mold compound Samsung Cheil SI7200DXC is qualified.

ISSUED BY RELIABILITY DEPARTMENT	Page 3 of 21
----------------------------------	--------------



Date:	May '06
No	01a/06

Test Vehicles:

Product Lines Power Mos Main Sales Types

 EZ52
 STP5NK50Z

 EZ62
 STP4NK60Z

 MD65
 STP11NM60

 ED7H
 STP75NF75

 ED6F
 STP60NF06

Product Lines Power Bipolar Main Sales Types

B004 TIP122 BV22 BUL128

ISSUED BY RELIABILITY DEPARTMENT Page 4 of 21



Date:	May '06
No	01a/06

Failure Criteria:

A failed component is a device which becomes inoperative during the test or it fails on meeting the end limits foreseen in the device specification, for one or more than the parameters here below reported

Parameter Power MOS

Drain Leakage Current (Idss)
Gate Leakage Current (Igss)
Threshold Voltage (Vgs(th)
Forward On Voltage (Vsd)
Drain Source On Voltage (Vds(on))
Drain Source Breakdown Voltage (Bvdss)

Parameter Power BIP

Collector Leakage Current (Icbo or Iceo or Ices, etc...) Emitter Leakage (Iebo) HFE, Vcesat, Vbesat, Vf Breakdown Voltage (BVcbo, BVceo, Vbces, Bvebo)



Date:	May '06
No	01a/06

Reliability Evaluation Plan and results

D.U.T.: STP5NK50Z LINE: EZ52 PACKAGE: TO-220

Test	Conditions	S.S.	Requirement	Results
H.T.S.	TA=150℃	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
T.H.B.	TA=85℃ - RH=85% Vbias= 100V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.R.B.	T.A.=150℃ Vdd=400V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.F.B.	TA=150℃ Vgss=30V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
PRESSURE POT	TA=121℃ - PA=2Atm	77 x 1 Lot	Parameter deviation within spec. limits at 96 hours.	No parameter deviation out of spec. limits at 96 hours.
THERMAL CYCLES AIR TO AIR	TA=-65℃ TO 150℃ 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation out of spec. limits at 500 cy
THERMAL FATIGUE	ΔTC=105℃ - Pd=4.8W	77 x 1 Lot	Parameter deviation within spec. limits at 10k cycles.	No parameter deviation out of spec. limits at 10Kcy.

ISSUED BY	RELIABILITY DEPARTMENT	Page 6 of 21
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Date:	May '06
No	01a/06

Reliability Evaluation Plan and results

D.U.T.: STP4NK60Z LINE: EZ62 PACKAGE: TO-220

Test	Conditions	S.S.	Requirement	Results
H.T.S.	TA=150℃	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
T.H.B.	TA=85℃ - RH=85% Vbias= 100V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.R.B.	T.A.=150℃ Vdd=480V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.F.B.	TA=150℃ Vgss=30V	77 x 1 Lot	Parameter deviation within spec limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
PRESSURE POT	TA=121℃ - PA=2Atm	77 x 1 Lot	Parameter deviation within spec. limits at 96 hours.	No parameter deviation out of spec. limits at 96 hours.
THERMAL CYCLES AIR TO AIR	TA=-65℃ TO 150℃ 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation out of spec. limits at 500 cy
THERMAL FATIGUE	ΔTC=105℃ - Pd=4.8W	77 x 1 Lot	Parameter deviation within spec. limits at 10k cycles.	No parameter deviation out of spec. limits at 10Kcy.

ISSUED BY	RELIABILITY DEPARTMENT	Page 7 of 21
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Date:	May '06
No	01a/06

Reliability Evaluation Plan and results

D.U.T.: STP11NM60 LINE: MD65 PACKAGE: TO-220

Test	Conditions	S.S.	Requirement	Results
H.T.S	TA=150℃	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
T.H.B.	TA=85℃ - RH=85% Vbias = 100V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.R.B.	T.A.=150℃ ; Vdd=480 V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.F.B.	TA = 150℃ Vgss= 30V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
PRESSURE POT	TA=121℃ - PA=2Atm	77 x 1 Lot	Parameter deviation within spec. limits at 96 hours.	No parameter deviation out of spec. limits at 96 hours.
THERMAL CYCLES AIR TO AIR	TA=-65℃ TO +150℃ 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation out of spec. limits at 500 cycles.
THERMAL FATIGUE	ΔTC=105℃ - Pd=4.8W	77 x 1 Lot	Parameter deviation within spec. limits at 10k cycles.	No parameter deviation out of spec. limits at 10Kcy.

ISSUED BY	RELIABILITY DEPARTMENT	Page 8 of 21
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Date:	May '06
No	01a/06

Reliability Evaluation Plan and results

D.U.T.: STP75NF75 LINE: ED7H PACKAGE: TO-220

Test	Conditions	S.S.	Requirement	Results
H.T.S	TA=175℃	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
T.H.B.	TA=85℃ - RH=85% Vbias = 50V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.R.B.	T.A.=175℃ ; Vdd=60 V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.F.B.	TA = 150℃ Vgss= 20V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
PRESSURE POT	TA=121℃ - PA=2Atm	77 x 1 Lot	Parameter deviation within spec. limits at 96 hours.	No parameter deviation out of spec. limits at 96 hours.
THERMAL CYCLES AIR TO AIR	TA=-65℃ TO +150℃ 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation out of spec. limits at 500 cycles.
THERMAL FATIGUE	ΔTC=105℃ - Pd=4.8W	77 x 1 Lot	Parameter deviation within spec. limits at 10k cycles.	No parameter deviation out of spec. limits at 10Kcy.

ISSUED BY	RELIABILITY DEPARTMENT	Page 9 of 21
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Date:	May '06
No	01a/06

Reliability Evaluation Plan and results

D.U.T.: STP60NF06 LINE: ED6F PACKAGE: TO-220

Test	Conditions	S.S.	Requirement	Results
H.T.S	TA=175℃	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
T.H.B.	TA=85℃ - RH=85% Vbias = 50V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.R.B.	T.A.=175℃ ; Vdd=48 V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.F.B.	TA = 150℃ Vgss= 20V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
PRESSURE POT	TA=121℃ - PA=2Atm	77 x 1 Lot	Parameter deviation within spec. limits at 96 hours.	No parameter deviation out of spec. limits at 96 hours.
THERMAL CYCLES AIR TO AIR	TA=-65℃ TO +150℃ 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation out of spec. limits at 500 cycles.
THERMAL FATIGUE	ΔTC=105℃ - Pd=4.8W	77 x 1 Lot	Parameter deviation within spec. limits at 10k cycles.	No parameter deviation out of spec. limits at 10Kcy.

ISSUED BY	RELIABILITY DEPARTMENT	Page 10 of 21
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Date:	May '06
No	01a/06

Reliability Evaluation Plan and results

D.U.T.: TIP122 Line: B004 Package: TO220

Test	Conditions	S.S.	Requirement	Results
H.T.R.B.	Ta=150℃ - Vces=80V	77x1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.S.	Ta=150℃	77x1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
T.H.B.	Ta=85℃; Rh=85%; Vces= 50V	77x1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
PRESSURE POT	Ta=121℃;Pa=2Atm	77x1 Lot	Parameter deviation within spec. limits at 96 hours.	No parameter deviation out of spec. limits at 96 hours.
THERMAL CYCLES AIR TO AIR	TA=-65℃ TO +150℃ 1 HOUR / CYCLE	77x1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation out of spec. limits at 500 cy
THERMAL FATIGUE	ΔTC=105℃ - Pd=4.8W	77x1 Lot	Parameter deviation within spec. limits at 10k cycles.	No parameter deviation out of spec. limits at 10Kcy.

ISSUED BY	RELIABILITY DEPARTMENT	Page 11 of 21
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Date:	May '06
No	01a/06

Reliability Evaluation Plan and results

D.U.T.: BUL128 LINE: BV22 PACKAGE: TO-220

Test	Conditions	S.S.	Requirement	Results
H.T.S.	Ta=150℃	77 x 1 Lot	Parameter deviation within spec limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
T.H.B.	Ta=85℃ - RH=85% Vbias= 100V (Vces)	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.R.B.	Ta=125℃ Vbias= 560V (Vces)	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
PRESSURE POT	Ta=121℃ - Pa=2Atm	77 x 1 Lot	Parameter deviation within spec. limits at 96 hours.	No parameter deviation out of spec. limits at96 hours.
THERMAL CYCLES AIR TO AIR	Ta=-65℃ TO 150℃ 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation out of spec. limits at 500 cy
THERMAL FATIGUE	ΔTC=105℃ - Pd=4.8W	77 x 1 Lot	Parameter deviation within spec. limits at 10k cycles.	No parameter deviation out of spec. limits at 10Kcy.

ISSUED BY	RELIABILITY DEPARTMENT	Page 12 of 21
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Date:	May '06
No	01a/06

Technological Characteristics

D.U.T.: STP5NK50Z LINE: EZ52 PACKAGE: TO-220

DIE			SFET Passivation : Dimensions :	_
DIE ATTACH	Soft Solder	FRAME	Frame and lead material: Frame coating : Lead coating :	Raw copper Ni/Ni Plate Sn 100%
WIRE BOND	Ultrasonic	WIRE	Material : Diameter :	Gate: Al/Mg Source: Al/Mg 5 mils Gate 5 mils Source
SEALING	Molding	PACKAGING	Material :	Epoxy Resin

PRODUCTION PLACES: WAFER PROCESSING: SINGAPORE

ISSUED BY	RELIABILITY DEPARTMENT	Page 13 of 21
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Date:	May '06
No	01a/06

Technological Characteristics

D.U.T.: STP4NK60Z LINE: EZ62 PACKAGE: TO-220

DIE	Technology: Material: Metallization – Front : - Back :	SuperMESH TM MO Silicon Al/Si (1%) Ti-Ni-Au	SFET Passivation : Dimensions :	2
DIE ATTACH	Soft Solder	FRAME	Frame and lead material: Frame coating : Lead coating :	Raw copper Ni/Ni Plate Sn 100%
WIRE BOND	Ultrasonic	WIRE	Material : Diameter :	Gate: Al/Mg Source: Al/Mg 5 mils Gate 5 mils Source
SEALING	Molding	PACKAGING	Material :	Epoxy Resin

PRODUCTION PLACES: WAFER PROCESSING: SINGAPORE

ISSUED BY	RELIABILITY DEPARTMENT	Page 14 of 21
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Date:	May '06
No	01a/06

Technological Characteristics

D.U.T.: STP11NM60 LINE: MD65 PACKAGE: TO-220

DIE	Technology: Material: Metallization – Front : - Back :	MD MESH TM MOSF Silicon Al/Si (1%) Ti-Ni-Au	FET Passivation : Dimensions :	
DIE ATTACH	Soft Solder	FRAME	Frame and lead material: Frame coating : Lead coating :	Raw copper Ni/Ni Plate Sn 100%
WIRE BOND	Ultrasonic	WIRE	Material : Diameter :	Gate: Al/Mg Source: Al 5 mils Gate 10 mils Source
SEALING	Molding	PACKAGING	Material :	Epoxy Resin

PRODUCTION PLACES: WAFER PROCESSING: CATANIA and SINGAPORE

ISSUED BY	RELIABILITY DEPARTMENT	Page 15 of 21
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Date:	May '06
No	01a/06

Technological Characteristics

D.U.T.: STP75NF75 Line: ED7H Package: TO-220

DIE			FET TM II Power MO Passivation : Dimensions :	None
DIE ATTACH	Soft solder	FRAME	Frame and lead material: Frame coating : Lead coating :	Raw copper Ni/Ni Plate Sn 100%
WIRE BOND	Ultrasonic	WIRE	Material : Diameter :	Al Gate Al Source 5 mils Gate 15 mils Source
SEALING	Molding	PACKAGING	Material :	Epoxy Resin

PRODUCTION PLACES: WAFER PROCESSING: SINGAPORE

ISSUED BY	RELIABILITY DEPARTMENT	Page 16 of 21
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Date:	May '06
No	01a/06

Technological Characteristics

D.U.T.: STP60NF06 Line: ED6F Package: TO-220

DIE			FET TM II Power MOS Passivation : Dimensions :	None
DIE ATTACH	Soft solder	FRAME	Frame and lead material: Frame coating: Lead coating:	Raw copper Ni/Ni Plate Sn 100%
WIRE BOND	Ultrasonic	WIRE	Material : Diameter :	Al Gate Al Source 5 mils Gate 15 mils Source
SEALING	Molding	PACKAGING	Material :	Epoxy Resin

PRODUCTION PLACES: WAFER PROCESSING: SINGAPORE

ISSUED BY	RELIABILITY DEPARTMENT	Page 17 of 21
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Date:	May '06
No	01a/06

Technological Characteristics

D.U.T.: TIP122 Line: B004 Package: TO220

DIE			Passivation :	P-Vapox 2510 x 2100 μm
			Frame and lead material:	Raw copper
DIE ATTACH	Soft solder	FRAME	Frame coating :	Ni/Ni Plated
			Lead coating:	Sn 100%
WIRE BOND	Ultrasonic	WIRE	Material :	Al/Mg - Base Al/Mg - Emitter
			Diameter :	5 mils - Base 7 mils - Emitter
SEALING	Molding	PACKAGING	Material :	Epoxy Resin

PRODUCTION PLACES: WAFER PROCESSING : SINGAPORE

ISSUED BY	RELIABILITY DEPARTMENT	Page 18 of 21
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Date:	May '06
No	01a/06

Technological Characteristics

D.U.T.: BUL128 Line: BV22 Package: TO-220

DIE	Technology: Material: Metallization – Front : - Back :	SILICON Al/Si	LTAGE STANDARD Passivation : Dimensions :	
DIE ATTACH	Soft solder	FRAME	Frame and lead material: Frame coating : Lead coating :	Raw copper Ni/Ni Plated Sn 100%
WIRE BOND	Ultrasonic	WIRE	Material : Diameter :	Al/Mg Base Al/Mg Emitter 5 mils
SEALING	Molding	PACKAGING	Material :	EPOXY RESIN

PRODUCTION PLACES: WAFER PROCESSING : SINGAPORE

ISSUED BY RELIABILITY DEPARTMENT Page 19 of 21
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Date:	May '06
No	01a/06

Reliability Test Description

High Temperature Reverse Bias (HTRB)

This test is performed in order to demonstrate the quality and reliability of devices subjected to an elevated temperature and simultaneously reverse biased. The purpose of this test is to detect surface defects such as poor passivation, presence of contaminants, etc...

High Temperature Forward Bias (HTFB)

This test is performed in order to demonstrate the quality and reliability of devices subjected to an elevated temperature and simultaneously forward gate biased. The purpose of this test is to detect surface and gate oxide defects.

High Temperature Storage (HTS)

This stress test is performed to check the device life in a high temperature ambient. Specimens are put for a period of time inside a stove in free air. Detectable failure mechanisms are presence of contaminants and metal corrosion.

Thermal Cycles/Shocks

The purpose of this test is to determine the resistance of devices to exposure to extreme changes in temperature. Specimens are first placed in a suitable environment at a low temperature and then transferred to one at high temperature. Effects of thermal cycles/shocks include cracking of die, breaking of wire bonding, mechanical damage to the device case.

ISSUED BY RELIABILITY DEPARTMENT Page 20 of 21
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Date:	May '06
No	01a/06

Reliability Test Description (continued)

Temperature Humidity Bias (THB)

This test is performed to check the device life in a high humidity ambient. Specimens are subjected to a permanent bias in a climatic chamber in the presence of steam. Detectable failure mechanisms are metal corrosion and moulding defects.

Pressure Pot

This test is performed in order to check device life in a high humidity ambient in an accelerated way. Specimens are subjected for a period of time inside an autoclave in the presence of steam and pressure. Detectable failure mechanism is metal corrosion.

Thermal Fatigue

This test is performed to demonstrate the quality and reliability of devices exposed to cyclic variation in electrical stress between "on" and "off" conditions and resultant cyclic variation in device and case temperatures (thermo-mechanical stress). The purpose of this test is to detect assembly defects: improper die-attach, bonding weakness and thermal mismatch among various components of the package.

Environmental Sequence

The purpose of this test is to study the influence of corrosion mechanism when the die/package system has already been stressed by temperature cycling.

ISSUED BY	RELIABILITY DEPARTMENT	Page 21 of 21
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MPA (Micro, Power, Analog) Group Voltage Regulator, Interface, Advanced logic & Power RF Quality Assurance & Reliability

Reliability Evaluation Plan and final results on LM317

SI7200DXY Molding compound

REL-6337-098.06W Line...... L317

Package... TO220

Test	Conditions	S.S.	Requirement	Results
H.T.S.	TA=150 °C	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation at 1000 hours.
T.H.B.	TA=85°C - RH=85% Vbias= 24V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation at 1000 hours.
H.T.B.	TA=125°C - Vdd= 35V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation at 1000 hours.
PRESSURE POT	TA=121°C - PA=2Atm	77 x 1 Lot	Parameter deviation within spec. limits at 168 hours.	No parameter deviation at 168 hours.
THERMAL CYCLES AIR TO AIR	TA=-65°C TO 150°C 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation at 500 cy
THERMAL SHOCKS LIQUID TO LIQUID	TA=-65°C TO 150°C 10 MIN / SHOCK	77 x 1 Lot	Parameter deviation within spec. limits at 500 shocks.	No parameter deviation at 500 sh.

 $\pmb{Comments}{:} \ \ \textit{The reliability tests results are positive}$

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